

	Type	Hits	Search Text	DBs
1	BRS	3	5590461.pn. or 5534666.pn. or 5373191.pn.	USPAT; JPO
2	BRS	1288	(29/830 or 428/901 or 174/260 or 174/250 or 361/760 or 361/784 or 361/792 or 361/794) and pad and (insulat\$3 or dielectric or resin) with (pad or post or metal adj column)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	10	5906042.pn. or 03289139.pn. or 60177671.pn. or 5181087.pn. or 5654232.pn. or 5373191.pn. or 4818728.pn. or 5373191.pn. or 5655200.pn. or 5842628.pn. or 5292689.pn.	USPAT; JPO
4	BRS	1	5844168.pn. and ground near pad	USPAT; JPO
5	BRS	22	"5424245"	USPAT
6	BRS	227	(257/737 or 257/690 or 257/700 or 257/738 or 257/774 or 257/776) and multi near layer and gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	90	(257/779 or 257/780 or 257/782 or 257/784 or 438/613 or 438/629) and multi near layer and gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	68	(438/637 or 438/639 or 438/640 or 438/667 or 438/700 or 438/713 or 438/701) and multi near layer and gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	1	"09066083"	USPAT; JPO
10	BRS	1	"09063083"	USPAT; JPO
11	BRS	1	"6111906"	USPAT; JPO
12	BRS	1	"5031993".PN.	USPAT
13	BRS	1	"5033053".PN.	USPAT

	Type	Hits	Search Text	DBs
14	BRS	1	"5930278".PN.	USPAT
15	BRS	1	"5981307".PN.	USPAT
16	BRS	14	"5033053"	USPAT; JPO
17	BRS	395	metal near (plug or layer or pad) with (resin or epoxy or polyimide) with coating	USPAT
18	BRS	27	"4816323"	USPAT
19	BRS	43947	(interposer or interconnector or distributor)	USPAT
20	BRS	6993	(interposer or interconnector or distributor) and gap	USPAT
21	BRS	1670	(semiconductor or IC or chip or die) and (interposer or interconnector or distributor) and gap	USPAT
22	BRS	75	(semiconductor or IC or chip or die) and (interposer or interconnector or distributor) and gap and (resin or polyimide or epoxy) with (coat or coating)	USPAT
23	BRS	20680	(semiconductor or IC or chip or die) and (resin or polyimide or epoxy) with (coat or coating)	USPAT
24	BRS	437	(semiconductor or IC or chip or die) and ((resin or polyimide or epoxy) near (metal or conductive)) with (coat or coating)	USPAT
25	BRS	72	(semiconductor or IC or chip or die) and ((resin or polyimide or epoxy) near (metal or conductive)) near (coat or coating)	USPAT
26	BRS	222	multi near layer and gap	JPO

	Type	Hits	Search Text	DBs
27	BRS	4	10069961.pn. or 5373191.pn. or 5534666.pn. or 4816323.pn.	USPAT; JPO